
200mA Low Power CMOS LDO

■ DESCRIPTION

The UP73XX-1 series is a set of three-terminal low power high voltage implemented in CMOS technology. They can deliver 200mA output current and allow an input voltage as high as 30V. They are available with several fixed output voltages ranging from 2.1V to 5.5V. CMOS technology ensure low voltage drop and low quiescent current

Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain variable voltages and currents

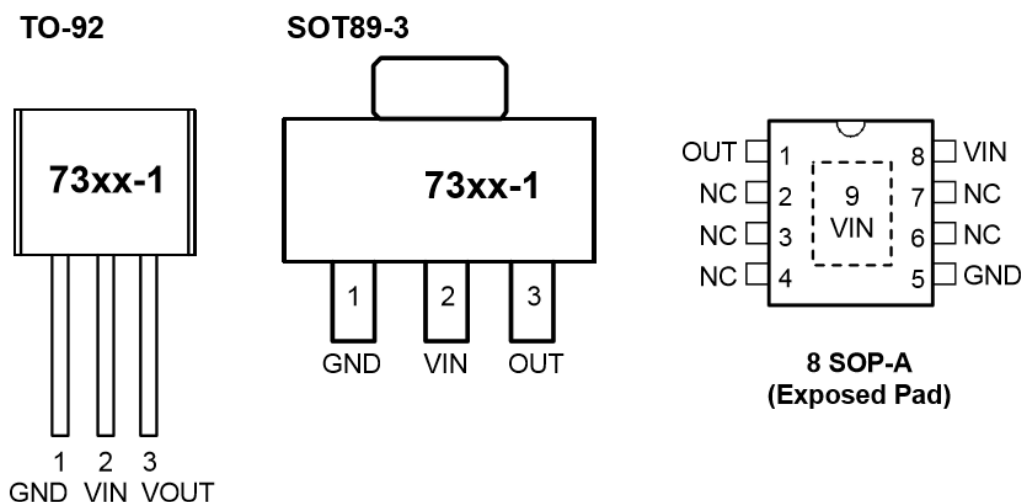
■ FEATURE

- ◆ *Low power consumption*
- ◆ *Low voltage drop*
- ◆ *Low temperature coefficient*
- ◆ *High input voltage 30V*
- ◆ *Quiescent current 2.5uA*
- ◆ *High output current 200mA*
- ◆ *Output voltage accuracy : tolerance 3%*
- ◆ *SOT89, TO92, SOT23-5 packages*

■ APPLICATIONS

- ◆ Battery-powered equipment
- ◆ Communication equipment
- ◆ Audio/Video equipment

■ PIN CONFIGURATION



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■ PART NUMBER INFORMATION

| | |
|---------------|--------------------------------------------------------------------------------------------------------------------------------------------|
| UP73XXA-1-BBC | XX=Voltage A=Package Code S: SOT89 T: TO92 s:SOT23-5L BB=Handing Code TR: Tape&Reel C=Lead Plating Code G: Green Product |
|---------------|--------------------------------------------------------------------------------------------------------------------------------------------|

■ ORDERING INFORMATION

| Part Number | Output Voltage | Package | Marking |
|---------------|----------------|----------|--------------|
| UP7350S-1-TRG | 5.0 | SOT89 | 1000EA / T&R |
| UP7350T-1-TRG | 5.0 | TO92 | 500EA / BAG |
| UP7350s-1-TRG | 5.0 | SOT23-5L | 3000EA / T&R |

■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

| Symbol | Parameter | Typical | Unit |
|---------------|--------------------------------|----------|------------------|
| $V_{IN(MAX)}$ | Supply Voltage | 35 | V |
| T_J | Operation Junction Temperature | 150 | $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | -55~+150 | $^\circ\text{C}$ |
| T_P | Operation Temperature | -40~+80 | $^\circ\text{C}$ |

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress rating only and functional device operation is not implied

■ THERMAL DATA

| Symbol | Parameter | Package | Max | Unit |
|-----------------|----------------------------------------|----------|-----|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance-Junction to Ambient | SOT23-3L | 500 | $^\circ\text{C}/\text{W}$ |
| | | SOT89 | 200 | $^\circ\text{C}/\text{W}$ |
| | | TO92 | 200 | $^\circ\text{C}/\text{W}$ |
| P_D | Power Dissipation | SOT23-3L | 0.2 | W |
| | | SOT89 | 0.5 | W |
| | | TO92 | 0.5 | W |

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■ **ELECTRICAL CHARACTERISTICS** ($T_A=25\text{ }^\circ\text{C}$ Unless otherwise noted)

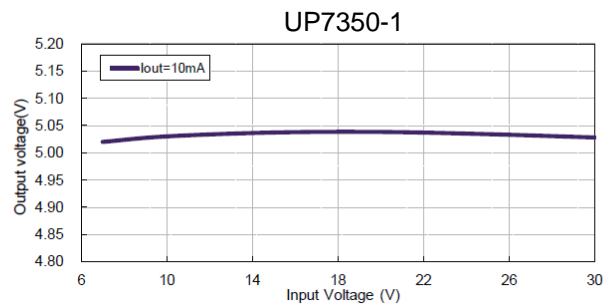
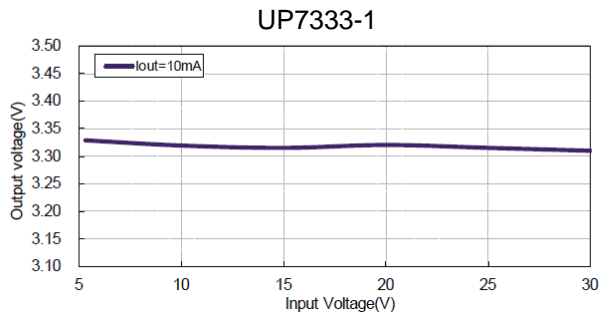
| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|----------------------------------------|-------------------|------------------------------------------------------|----------------|-----|----------------|------|
| V_{IN} | Input Voltage | | | | 30 | V |
| V_{OUT} | Output Voltage | $V_{IN}=V_{OUT}+2V, I_{OUT}=10mA$ | $V_{OUT}*0.97$ | | $V_{OUT}*1.03$ | V |
| I_{OUT} | Output Current | $V_{IN}=V_{OUT}+2V$ | 180 | 200 | | mA |
| ΔV_{OUT} | Load Regulation | $V_{IN}=V_{OUT}+2V,$ $1mA \leq I_{OUT} \leq 50mA$ | | 25 | 60 | mV |
| V_{DIF} | Dropout Voltage | $I_{OUT}=1mA, \Delta V_{OUT}=2\%$ | | 30 | 100 | mV |
| I_{SS} | Quiescent Current | No Load | | 2.2 | 4.0 | uA |
| $\Delta V_{OUT}/\Delta V_{IN}*V_{OUT}$ | Line Regulation | $V_{OUT}+1V \leq V_{IN} \leq 30V,$ $I_{OUT}=1mA$ | | | 0.2 | %V |

Note: Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at $V_{IN}=V_{OUT}+2V$ with a fixed load

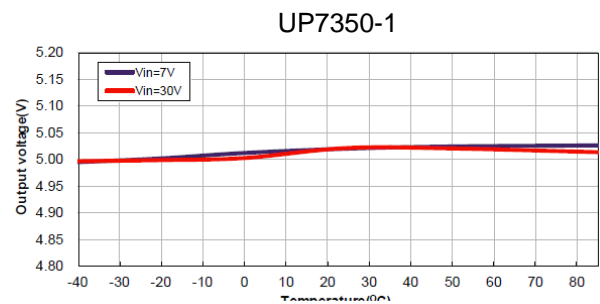
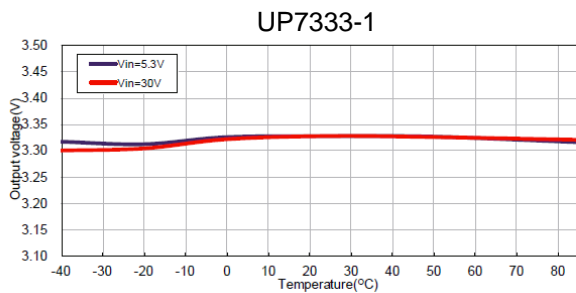
TYPICAL PERFORMANCE CHARACTERISTICS

Test Condition : $V_{IN}=V_{OUT}+2V$, $I_{OUT}=10mA$, $T_J=25^{\circ}C$, unless otherwise noted

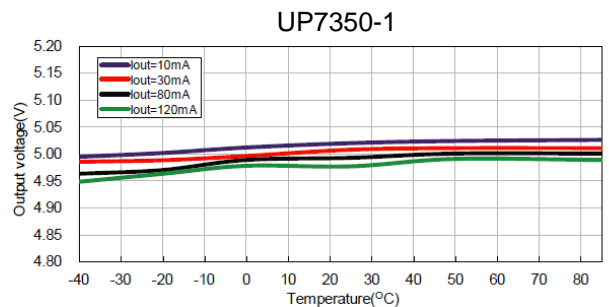
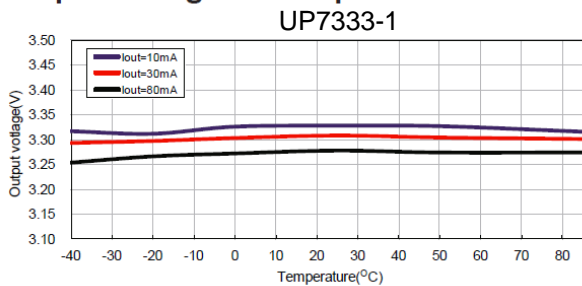
Output Voltage vs Input Voltage



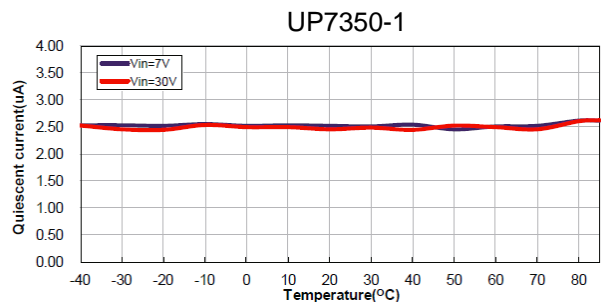
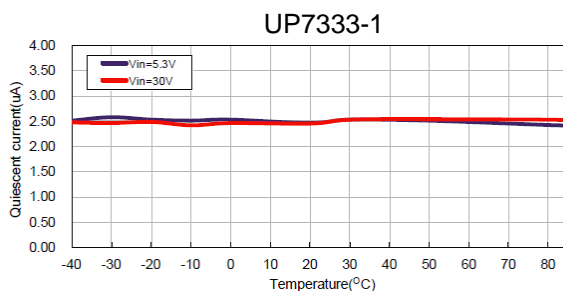
Output Voltage vs Temperature



Output Voltage vs Temperature



Quiescent current (I_{out}=0mA) vs Temperature



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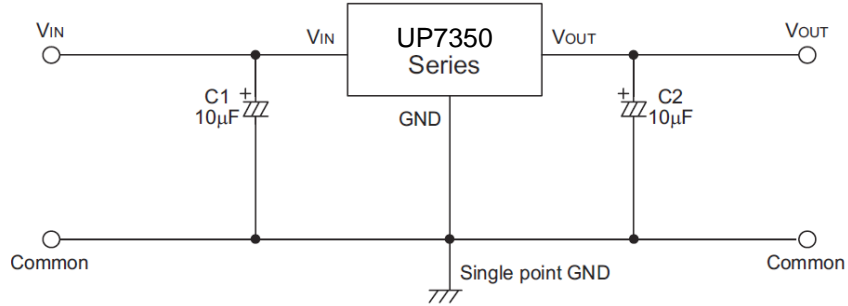
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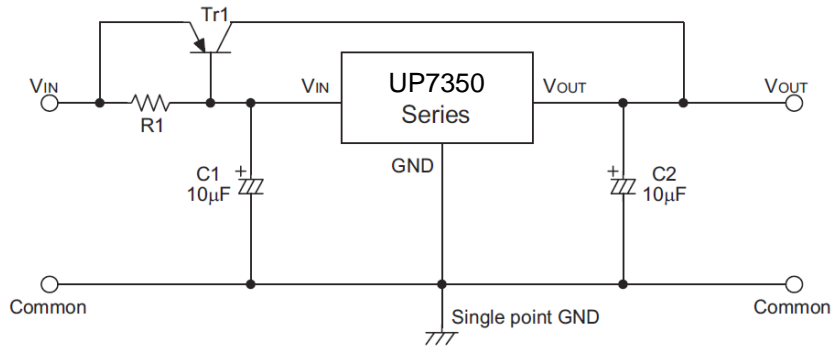
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APPLICATION CIRCUITS

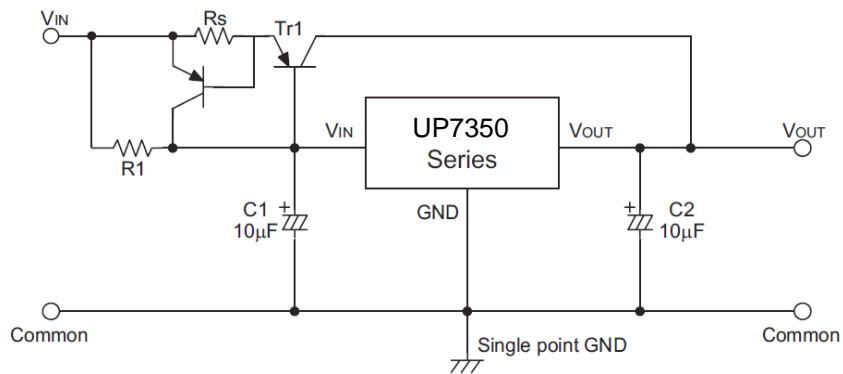
Basic Circuit



High Output Current Positive Voltage Regulator



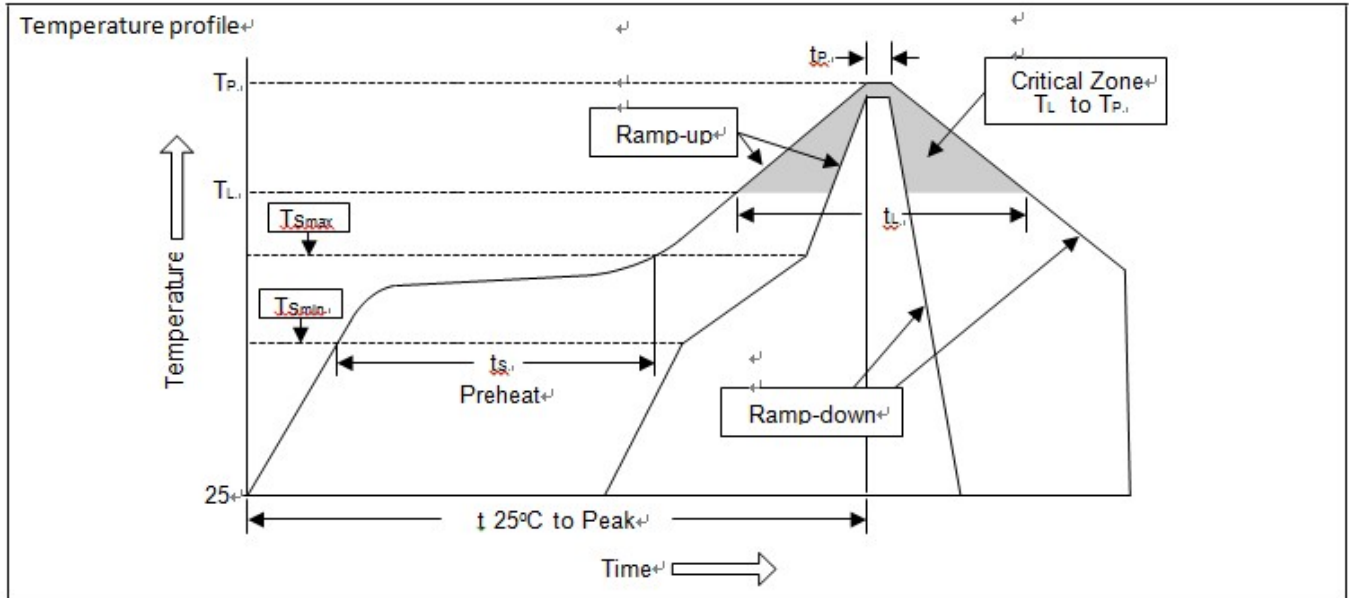
Short-Circuit Protection for $Tr1$



■ SOLDERING METHODS FOR UNIVERCHIP

Storage environment Temperature=10°C~35°C Humidity=65%±15%

Reflow soldering of surface mount device



| Profile Feature | Sn-Pb Eutectic Assembly | Pb free Assembly |
|--------------------------------------------------------------|-------------------------|------------------|
| Average ramp-up rate (T _L to T _P) | <3°C/sec | <3°C/sec |
| Preheat | | |
| -Temperature Min (T _{Smin}) | 100°C | 150°C |
| -Temperature Max (T _{Smax}) | 150°C | 200°C |
| -Time (min to max) (t _s) | 60~120 sec | 60~180 sec |
| T _{Smax} to T _L | | |
| -Ramp-up Rate | <3°C/sec | <3°C/sec |
| Time maintained above | | |
| -Temperature (T _L) | 183°C | 217°C |
| -Time (t _L) | 60~150 sec | 60~150 sec |
| Peak Temperature (T _P) | 240°C+0/-5°C | 260°C+0/-5°C |
| Time within 5°C of actual Peak Temperature (t _p) | 10~30 sec | 20~40 sec |
| Ramp-down Rate | <6°C/sec | <6°C/sec |
| Time 25°C to Peak Temperature | <6 minutes | <6 minutes |

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Flow (wave) soldering (solder dipping)

| Product | Peak Temperature | Dipping Time |
|----------------|------------------|--------------|
| Pb device | 245°C±5°C | 5sec±1sec |
| Pb-Free device | 260°C+0/-5°C | 5sec±1sec |



This integrated circuit can be damaged by ESD UniverChip Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedure can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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